

07-13-1998



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<p>1. Name of conveying party(ies):</p> <p style="text-align: center;"><i>UED</i> <i>6-24-98</i></p> <p>Yoshihisa NAGANO Eiji FUJII Yasuhiro UEMOTO</p> <p>Additional name(s) of conveying party(ies) attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No</p>	<p>2. Name and address of receiving party(ies):</p> <p>Matsushita Electronics Corporation 1-1, Saiwai-cho, Takatsuki-shi Osaka 569-1143 Japan</p> <p>Additional name(s) & address(es) attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No</p>
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3. Nature of conveyance:

Assignment Merger
 Security Agreement Change of Name
 Other:

Execution Date: June 18, 1998

4. Application number(s) or patent number(s): *09/103,961*

If this document is being filed together with a new application, the execution date of the application is: June 18, 1998

A. Patent Application No.(s) B. Patent No.(s)

Additional numbers attached? Yes No

<p>5. Name and address of party to whom correspondence concerning document should be mailed:</p> <p>Name: Douglas P. Mueller Address: Merchant, Gould, Smith, Edell, Welter & Schmidt, P.A. 3100 Norwest Center 90 South Seventh Street Minneapolis, MN 55402-4131</p>	<p>6. Total number of applications and patents involved: 1</p> <p>7. Total fee (37 CFR 3.41): \$40.00 <input checked="" type="checkbox"/> Enclosed <input type="checkbox"/> Authorized to be charged to deposit account</p> <p>8. Please charge any additional fees or credit any overpayments to our Deposit account number: 13-2725</p>
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To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Douglas P. Mueller *[Signature]* June 24, 1998
Name of Person Signing Signature Date

Total number of pages including cover sheet, attachments, and document: 3

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PATENT
REEL: 9295 FRAME: 0101

INSTRUCTIONS

INTERNATIONAL ASSIGNMENT TO CORPORATION

WHEREAS,

Inventor(s) Name,
Address, Citizenship

1. Yoshihisa NAGANO residing at 2-1-C-11-203, Takemidai, Suita-shi, Osaka 565-0863, JAPAN and a citizen of Japan;
2. Eiji FUJII residing at 2-3-808, Shirakawa 3-chome, Ibaraki-shi, Osaka 567-0832, JAPAN and a citizen of Japan;
3. Yasuhiro UEMOTO residing at 2-31, Nakanosho 2-chome, Otsu-shi, Shiga 520-0837, JAPAN and a citizen of Japan;
4. _____ residing at _____ and a citizen of _____;
5. _____ residing at _____ and a citizen of _____;
6. _____ residing at _____ and a citizen of _____;
7. _____ residing at _____ and a citizen of _____;
8. _____ residing at _____ and a citizen of _____;
9. _____ residing at _____ and a citizen of _____;

Date Patent Declaration
Signed and Title
Serial No. and filing
date (if known)

(herein called "THE UNDERSIGNED") have made an invention and have executed an application for Letters Patent of the United States on _____ for this invention, which application is entitled

METHOD FOR MANUFACTURING SEMICONDUCTOR DEVICE

_____ and which has been given Serial Number _____ and the filing date of _____;

Name of Corporation

AND WHEREAS Matsushita Electronics Corporation (herein called "ASSIGNEE"), a corporation organized under the laws of Japan and having an office and place of business at 1-1, Saiwai-cho, Takatsuki-shi, Osaka 569-1143, Japan

State or Country of
Incorporation and Address

wishes to acquire the entire right, title and interest in and to said invention and patent application and any Letters Patent to be obtained therefor;

NOW, THEREFORE, for and in consideration of the sum of One Dollar and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, THE UNDERSIGNED hereby sell, assign and transfer to the ASSIGNEE, its successors and assigns, the entire right, title and interest for all countries in and to the invention disclosed in the aforesaid application, and in and to the said application, all divisions, continuations, or renewals thereof, all Letters Patent which may be granted therefrom, and all reissues or extensions of such patents; and THE UNDERSIGNED hereby authorize and request the Commissioner of Patents to issue any and all United States Letters Patent for the aforesaid invention to the ASSIGNEE of the entire right, title and interest in and to the same, for the use of the ASSIGNEE, its successors and assigns.

THE UNDERSIGNED hereby agree that THE UNDERSIGNED, their executors and legal representatives will make, execute and deliver (without charge but at the expense of the ASSIGNEE) any and all other instruments in writing including any and all further application papers, affidavits, assignments and other documents, and will communicate to said ASSIGNEE, its successors and representatives all facts known to THE UNDERSIGNED relating to said invention and the history thereof and will testify in all legal proceedings and generally do all things which may be necessary or desirable to vest the ASSIGNEE, its successors or assigns the entire right, title and interest in and to the said invention, applications, Letters Patent, rights, titles, benefits, privileges and advantages hereby sold, assigned and conveyed, or intended so to be.

THE UNDERSIGNED represent and agree with said ASSIGNEE its successors and assigns, that no assignment grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been or will be made to others by THE UNDERSIGNED, and that full right to convey the same as herein expressed is possessed by THE UNDERSIGNED.

IN TESTIMONY WHEREOF, THE UNDERSIGNED have hereunto set their hand on the dates indicated below.

Each inventor must sign & date

Note: No legalization or other witness required

<u>Yoshihisa Nagano</u> Signature	<u>June 17, 1998</u> Date
<u>[Signature]</u> Signature	<u>June 16, 1998</u> Date
<u>Yoshinori Yamoto</u> Signature	<u>June 18, 1998</u> Date
_____ Signature	_____ Date
_____ Signature	_____ Date
_____ Signature	_____ Date
_____ Signature	_____ Date
_____ Signature	_____ Date
_____ Signature	_____ Date